

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of: Ashjaee et al.	Group Art Unit: Not yet assigned
Serial No.: Not yet assigned	Examiner: Not yet assigned
Filed: February 25, 2004	Docket: NT-261C1-US
Title: Method Of Sealing Wafer Backside For Full-Face Processing	

**INFORMATION DISCLOSURE STATEMENT**

**US PATENT DOCUMENTS**

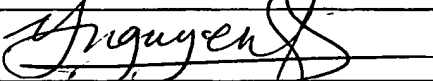
Examiner Initials	Cite No.	Document Number	Publication Date	Name of Patentee or Applicant	
GN	AA	6,290,577	Sep., 2001	Shendon et al.	In serial No. 09/910,686
	AB	6,228,233	May, 2001	Lakshmikanthan et al.	In serial No. 09/910,686
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**FOREIGN PATENT DOCUMENTS**

Examiner Initials	Cite No.	Document Number	Publication Date	Name of Patentee or Applicant		Translation

**OTHER DOCUMENTS**

Examiner Initials	Cite No.			Translation

Examiner Signature		Date Considered	02/25/05.
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